

Electrical Characteristics

Characteristic		Sym	Notes	Minimum	Typical	Maximum	Units		
Center Frequency, +25 °C	Absolute Frequency	f _C		433.870		433.970	MHz		
	Tolerance from 433.920 MHz	Δf_{C}				±50	kHz		
Insertion Loss		IL			1.5	2.2	dB		
Quality Factor	Unloaded Q	Q _U			9000				
	50 Ω Loaded Q	QL			1458				
Temperature Stability	Turnover Temperature	Т _О		10	25	40	°C		
	Turnover Frequency	f _O			f _C				
	Frequency Temperature Coefficient	FTC			0.032		ppm/°C ²		
Frequency Aging	Absolute Value during the First Year	f _A			≤10		ppm/yr		
DC Insulation Resistance between Any Two Terminals				1.0			MΩ		
RF Equivalent RLC Model	Motional Resistance	R _M			19.4		Ω		
	Motional Inductance	L _M			63.8		μH		
	Motional Capacitance	CM			2.11		fF		
	Shunt Static Capacitance	CO			2.4		pF		
Test Fixture Shunt Inductance		L _{TEST}			55.1		nH		
Lid Symbolization (in addition to Lot and/or Date Codes)		745, <u>YYWWS</u>							

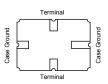


1. The design, manufacturing process, and specifications of this device are subject to change.

2. US or International patents may apply.

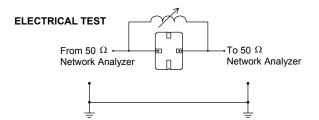
Electrical Connections

The SAW resonator is bidirectional and may be installed with either orientation. The two terminals are interchangeable and unnumbered. The callout NC indicates no internal connection. The NC pads assist with mechanical positioning and stability. External grounding of the NC pads is recommended to help reduce parasitic capacitance in the circuit.

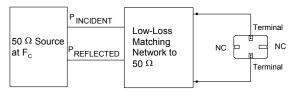


Typical Test Circuit

The test circuit inductor, L_{TEST} , is tuned to resonate with the static capacitance, C_0 , at F_C .



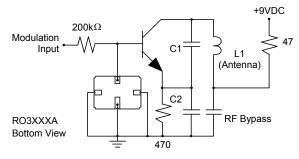
POWER TEST



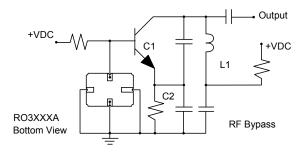
CW RF Power Dissipation = PINCIDENT - P REFLECTED

Typical Application Circuits

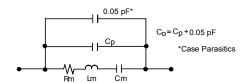
Typical Low-Power Transmitter Application



Typical Local Oscillator Applications

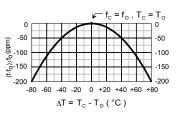


Equivalent Model

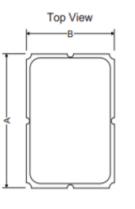


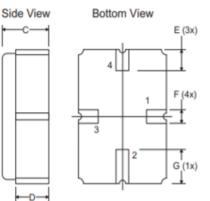
Temperature Characteristics

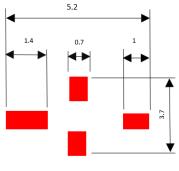
The curve shown on the right accounts for resonator contribution only and does not include LC component temperature contributions.



Case







PCB Footprint

Dimensions	N	lillimeter	s	Inches			
Dimensions	Min	Nom	Max	Min	Nom	Max	
A	4.87	5.00	5.13	0.191	0.196	0.201	
В	3.37	3.50	3.63	0.132	0.137	0.142	
С	1.45	1.53	1.60	0.057	0.060	0.062	
D	1.35	1.43	1.50	0.040	0.057	0.059	
E	0.67	0.80	0.93	0.026	0.031	0.036	
F	0.37	0.50	0.63	0.014	0.019	0.024	
G	1.07	1.20	1.33	0.042	0.047	0.052	

Recommended Reflow Profile

- 1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
- 2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
- 3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
- 4. Time: 5 times maximum.

